

Docket No. 0039-7292-2 DIV

IN RE APPLICATION OF: KAORI UMEZAWA, ET AL.

SERIAL NO: 09/358,388

RCE FILED: APRIL 18, 2002

FOR: SUBSTRATE HAVING SHALLOW TRENCH ISOLATION AND METHOD OF MANUFACTURING THE SAME

ASSISTANT COMMISSIONER FOR PATENTS

WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an amendment in the above-identified application.

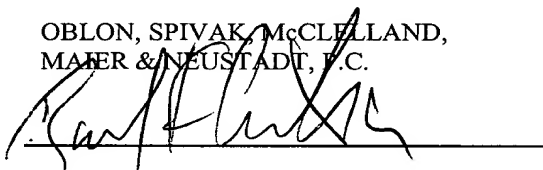
- ☐ No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 has been established by a verified statement previously submitted.
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 has been established by a verified statement submitted herewith.
- ☒ Additional documents filed herewith: PETITION FOR EXTENSION OF TIME (3 MONTHS), ATTACHMENT (12 pages)

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	42	MINUS	43	0	× \$18 =	\$0.00
INDEPENDENT	9	MINUS	9	0	× \$84 =	\$0.00
		<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS			+ \$280 =	\$0.00
		TOTAL OF ABOVE CALCULATIONS				\$0.00
		<input type="checkbox"/> Reduction by 50% for filing by Small Entity				\$0.00
		<input type="checkbox"/> Recordation of Assignment			+ \$40 =	\$0.00
		TOTAL				\$0.00

- ☒ A check in the amount of **\$920.00** is attached.
- ☒ Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- ☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

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0039-7292-2 DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

KAORI UMEZAWA ET AL.



GROUP ART UNIT: 2814

SERIAL NO: 09/358,388

RCE FILED: APRIL 18, 2002

: EXAMINER: MAI, A.

FOR: SUBSTRATE HAVING SHALLOW :
TRENCH ISOLATION AND METHOD
OF MANUFACTURING THE SAME

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Responsive to the Official Action mailed May 7, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend Claims 9, 25-33, 36, 41, and 44-46 as shown in the attached marked-up copy to read as follows:

- F₁
9. (Five times amended) A method of manufacturing a semiconductor substrate having shallow trench isolation regions and a device region sandwiched by the shallow trench isolation regions, comprising:
- (a) forming a plurality of grooves on part of a surface of the semiconductor substrate;
 - (b) depositing oxide films in the grooves by a CVD method using an electrically inert organic silicon source;

#3
R. H. F.
J. W. H.
11-19-02

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